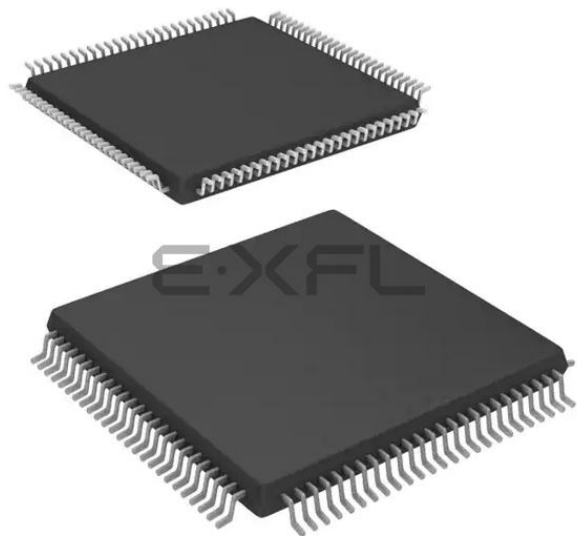




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Details

Product Status	Obsolete
Core Processor	ARM® Cortex®-M4
Core Size	32-Bit Single-Core
Speed	72MHz
Connectivity	CANbus, EBI/EMI, Ethernet, I ² C, IrDA, LINbus, MMC/SD/SDIO, QSPI, SmartCard, SPI, UART/USART, USB
Peripherals	Brown-out Detect/Reset, DMA, LCD, POR, PWM, WDT
Number of I/O	80
Program Memory Size	1MB (1M x 8)
Program Memory Type	FLASH
EEPROM Size	-
RAM Size	512K x 8
Voltage - Supply (Vcc/Vdd)	1.8V ~ 3.8V
Data Converters	A/D 16x12b SAR; D/A 2x12b
Oscillator Type	Internal
Operating Temperature	-40°C ~ 125°C (TA)
Mounting Type	Surface Mount
Package / Case	100-TQFP
Supplier Device Package	100-TQFP (14x14)
Purchase URL	https://www.e-xfl.com/product-detail/silicon-labs/efm32gg11b840f1024iq100-a

1. Feature List

The EFM32GG11 highlighted features are listed below.

- **ARM Cortex-M4 CPU platform**
 - High performance 32-bit processor @ up to 72 MHz
 - DSP instruction support and Floating Point Unit
 - Memory Protection Unit
 - Wake-up Interrupt Controller
- **Flexible Energy Management System**
 - 80 μ A/MHz in Active Mode (EM0)
 - 2.1 μ A EM2 Deep Sleep current (16 kB RAM retention and RTCC running from LFRCO)
- **Integrated DC-DC buck converter**
- **Up to 2048 kB flash program memory**
 - Dual-bank with read-while-write support
- **Up to 512 kB RAM data memory**
 - 256 kB with ECC (SEC-DED)
- **Octal/Quad-SPI Flash Memory Interface**
 - Supports 3 V and 1.8 V memories
 - 1/2/4/8-bit data bus
 - Quad-SPI Execute In Place (XIP)
- **Communication Interfaces**
 - Low-energy Universal Serial Bus (USB) with Device and Host support
 - Fully USB 2.0 compliant
 - On-chip PHY and embedded 5V to 3.3V regulator
 - Crystal-free Device mode operation
 - Patent-pending Low-Energy Mode (LEM)
 - SD/MMC/SDIO Host Controller
 - SD v3.01, SDIO v3.0 and MMC v4.51
 - 1/4/8-bit bus width
 - 10/100 Ethernet MAC with MII/RMII interface
 - IEEE1588-2008 precision time stamping
 - Energy Efficient Ethernet (802.3az)
 - Up to 2 $\times$ CAN Bus Controller
 - Version 2.0A and 2.0B up to 1 Mbps
 - 6 $\times$ Universal Synchronous/Asynchronous Receiver/ Transmitter
 - UART/SPI/SmartCard (ISO 7816)/IrDA/I2S/LIN
 - Triple buffered full/half-duplex operation with flow control
 - Ultra high speed (36 MHz) operation on one instance
 - 2 $\times$ Universal Asynchronous Receiver/ Transmitter
 - 2 $\times$ Low Energy UART
 - Autonomous operation with DMA in Deep Sleep Mode
 - 3 $\times$ I²C Interface with SMBus support
 - Address recognition in EM3 Stop Mode
- **Up to 144 General Purpose I/O Pins**
 - Configurable push-pull, open-drain, pull-up/down, input filter, drive strength
 - Configurable peripheral I/O locations
 - 5 V tolerance on select pins
 - Asynchronous external interrupts
 - Output state retention and wake-up from Shutoff Mode
- **Up to 24 Channel DMA Controller**
- **Up to 24 Channel Peripheral Reflex System (PRS) for autonomous inter-peripheral signaling**
- **External Bus Interface for up to 4x256 MB of external memory mapped space**
 - TFT Controller with Direct Drive
 - Per-pixel alpha-blending engine
- **Hardware Cryptography**
 - AES 128/256-bit keys
 - ECC B/K163, B/K233, P192, P224, P256
 - SHA-1 and SHA-2 (SHA-224 and SHA-256)
 - True Random Number Generator (TRNG)
- **Hardware CRC engine**
 - Single-cycle computation with 8/16/32-bit data and 16-bit (programmable)/32-bit (fixed) polynomial
- **Security Management Unit (SMU)**
 - Fine-grained access control for on-chip peripherals
- **Integrated Low-energy LCD Controller with up to 8 $\times$ 36 segments**
 - Voltage boost, contrast and autonomous animation
 - Patented low-energy LCD driver
- **Backup Power Domain**
 - RTCC and retention registers in a separate power domain, available down to energy mode EM4H
 - Operation from backup battery when main power absent/insufficient
- **Ultra Low-Power Precision Analog Peripherals**
 - 2 $\times$ 12-bit 1 Msamples/s Analog to Digital Converter (ADC)
 - On-chip temperature sensor
 - 2 $\times$ 12-bit 500 ksamples/s Digital to Analog Converter (VDAC)
 - Digital to Analog Current Converter (IDAC)
 - Up to 4 $\times$ Analog Comparator (ACMP)
 - Up to 4 $\times$ Operational Amplifier (OPAMP)
 - Robust current-based capacitive sensing with up to 64 inputs and wake-on-touch (CSEN)
 - Up to 108 GPIO pins are analog-capable. Flexible analog peripheral-to-pin routing via Analog Port (APORT)
 - Supply Voltage Monitor

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3.2.4 EM2 and EM3 Power Domains

The EFM32GG11 has three independent peripheral power domains for use in EM2 and EM3. Two of these domains are dynamic and can be shut down to save energy. Peripherals associated with the two dynamic power domains are listed in [Table 3.1 EM2 and EM3 Peripheral Power Subdomains on page 13](#). If all of the peripherals in a peripheral power domain are unused, the power domain for that group will be powered off in EM2 and EM3, reducing the overall current consumption of the device. Other EM2, EM3, and EM4-capable peripherals and functions not listed in the table below reside on the primary power domain, which is always on in EM2 and EM3.

Table 3.1. EM2 and EM3 Peripheral Power Subdomains

Peripheral Power Domain 1	Peripheral Power Domain 2
ACMP0	ACMP1
PCNT0	PCNT1
ADC0	PCNT2
LETIMER0	CSEN
LESENSE	VDAC0
APORT	LEUART0
-	LEUART1
-	LETIMER1
-	I2C0
-	I2C1
-	I2C2
-	IDAC
-	ADC1
-	ACMP2
-	ACMP3
-	LCD
-	RTC

3.3 General Purpose Input/Output (GPIO)

EFM32GG11 has up to 144 General Purpose Input/Output pins. GPIO are organized on three independent supply rails, allowing for interface to multiple logic levels in the system simultaneously. Each GPIO pin can be individually configured as either an output or input. More advanced configurations including open-drain, open-source, and glitch-filtering can be configured for each individual GPIO pin. The GPIO pins can be overridden by peripheral connections, like SPI communication. Each peripheral connection can be routed to several GPIO pins on the device. The input value of a GPIO pin can be routed through the Peripheral Reflex System to other peripherals. The GPIO subsystem supports asynchronous external pin interrupts.

3.4 Clocking

3.4.1 Clock Management Unit (CMU)

The Clock Management Unit controls oscillators and clocks in the EFM32GG11. Individual enabling and disabling of clocks to all peripheral modules is performed by the CMU. The CMU also controls enabling and configuration of the oscillators. A high degree of flexibility allows software to optimize energy consumption in any specific application by minimizing power dissipation in unused peripherals and oscillators.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output fall time, From 70% to 30% of V_{IO}	t_{IOF}	$C_L = 50\text{ pF}$, DRIVESTRENGTH ¹ = STRONG, SLEWRATE ¹ = 0x6	—	1.8	—	ns
		$C_L = 50\text{ pF}$, DRIVESTRENGTH ¹ = WEAK, SLEWRATE ¹ = 0x6	—	4.5	—	ns
Output rise time, From 30% to 70% of V_{IO}	t_{IOR}	$C_L = 50\text{ pF}$, DRIVESTRENGTH ¹ = STRONG, SLEWRATE = 0x6 ¹	—	2.2	—	ns
		$C_L = 50\text{ pF}$, DRIVESTRENGTH ¹ = WEAK, SLEWRATE ¹ = 0x6	—	7.4	—	ns

Note:
1. In GPIO_Pn_CTRL register.

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Note: 1. ACMPVDD is a supply chosen by the setting in ACMPn_CTRL_PWRSEL and may be IOVDD, AVDD or DVDD. 2. The total ACMP current is the sum of the contributions from the ACMP and its internal voltage reference. $I_{ACMPTOTAL} = I_{ACMP} + I_{ACMPREF}$. 3. ± 100 mV differential drive. 4. In ACMPn_CTRL register. 5. In ACMPn_HYSTERESIS registers. 6. In ACMPn_INPUTSEL register.						

4.1.18 Capacitive Sense (CSEN)

Table 4.26. Capacitive Sense (CSEN)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Single conversion time (1x accumulation)	t_{CNV}	12-bit SAR Conversions	—	20.2	—	μs
		16-bit SAR Conversions	—	26.4	—	μs
		Delta Modulation Conversion (single comparison)	—	1.55	—	μs
Maximum external capacitive load	C_{EXTMAX}	CS0CG=7 (Gain = 1x), including routing parasitics	—	68	—	pF
		CS0CG=0 (Gain = 10x), including routing parasitics	—	680	—	pF
Maximum external series impedance	R_{EXTMAX}		—	1	—	k Ω
Supply current, EM2 bonded conversions, WARMUP-MODE=NORMAL, WARMUPCNT=0	$I_{\text{CSEN_BOND}}$	12-bit SAR conversions, 20 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	326	—	nA
		Delta Modulation conversions, 20 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	226	—	nA
		12-bit SAR conversions, 200 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	33	—	nA
		Delta Modulation conversions, 200 ms conversion rate, CS0CG=7 (Gain = 1x), 10 channels bonded (total capacitance of 330 pF) ¹	—	25	—	nA
Supply current, EM2 scan conversions, WARMUP-MODE=NORMAL, WARMUPCNT=0	$I_{\text{CSEN_EM2}}$	12-bit SAR conversions, 20 ms scan rate, CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	690	—	nA
		Delta Modulation conversions, 20 ms scan rate, 8 comparisons per sample (DMCR = 1, DMR = 2), CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	515	—	nA
		12-bit SAR conversions, 200 ms scan rate, CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	79	—	nA
		Delta Modulation conversions, 200 ms scan rate, 8 comparisons per sample (DMCR = 1, DMR = 2), CS0CG=0 (Gain = 10x), 8 samples per scan ¹	—	57	—	nA

4.1.19 Operational Amplifier (OPAMP)

Unless otherwise indicated, specified conditions are: Non-inverting input configuration, VDD = 3.3 V, DRIVESTRENGTH = 2, MAIN-OUTEN = 1, C_{LOAD} = 75 pF with OUTSCALE = 0, or C_{LOAD} = 37.5 pF with OUTSCALE = 1. Unit gain buffer and 3X-gain connection as specified in table footnotes⁸ 1.

Table 4.27. Operational Amplifier (OPAMP)

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Supply voltage (from AVDD)	V _{OPA}	HCMDIS = 0, Rail-to-rail input range	2	—	3.8	V
		HCMDIS = 1	1.62	—	3.8	V
Input voltage	V _{IN}	HCMDIS = 0, Rail-to-rail input range	V _{VSS}	—	V _{OPA}	V
		HCMDIS = 1	V _{VSS}	—	V _{OPA} -1.2	V
Input impedance	R _{IN}		100	—	—	MΩ
Output voltage	V _{OUT}		V _{VSS}	—	V _{OPA}	V
Load capacitance ²	C _{LOAD}	OUTSCALE = 0	—	—	75	pF
		OUTSCALE = 1	—	—	37.5	pF
Output impedance	R _{OUT}	DRIVESTRENGTH = 2 or 3, 0.4 V ≤ V _{OUT} ≤ V _{OPA} - 0.4 V, -8 mA < I _{OUT} < 8 mA, Buffer connection, Full supply range	—	0.25	—	Ω
		DRIVESTRENGTH = 0 or 1, 0.4 V ≤ V _{OUT} ≤ V _{OPA} - 0.4 V, -400 μA < I _{OUT} < 400 μA, Buffer connection, Full supply range	—	0.6	—	Ω
		DRIVESTRENGTH = 2 or 3, 0.1 V ≤ V _{OUT} ≤ V _{OPA} - 0.1 V, -2 mA < I _{OUT} < 2 mA, Buffer connection, Full supply range	—	0.4	—	Ω
		DRIVESTRENGTH = 0 or 1, 0.1 V ≤ V _{OUT} ≤ V _{OPA} - 0.1 V, -100 μA < I _{OUT} < 100 μA, Buffer connection, Full supply range	—	1	—	Ω
Internal closed-loop gain	G _{CL}	Buffer connection	TBD	1	TBD	-
		3x Gain connection	TBD	2.99	TBD	-
		16x Gain connection	TBD	15.7	TBD	-
Active current ⁴	I _{OPA}	DRIVESTRENGTH = 3, OUTSCALE = 0	—	580	—	μA
		DRIVESTRENGTH = 2, OUTSCALE = 0	—	176	—	μA
		DRIVESTRENGTH = 1, OUTSCALE = 0	—	13	—	μA
		DRIVESTRENGTH = 0, OUTSCALE = 0	—	4.7	—	μA

4.1.25 External Bus Interface (EBI)

EBI Write Enable Output Timing

Timing applies to both EBI_WEn and EBI_NANDWEn for all addressing modes and both polarities. All numbers are based on route locations 0,1,2 only (with all EBI alternate functions using the same location at the same time). Timing is specified at 10% and 90% of IOVDD, 25 pF external loading, and slew rate for all GPIO set to 6.

Table 4.36. EBI Write Enable Timing

Parameter	Symbol	Test Condition	Min	Typ	Max	Unit
Output hold time, from trailing EBI_WEn / EBI_NANDWEn edge to EBI_AD, EBI_A, EBI_CS _n , EBI_BL _n invalid	t _{OH_WEn}	IOVDD ≥ 1.62 V	-22 + (WRHOLD * t _{HFCOR-ECLK})	—	—	ns
		IOVDD ≥ 3.0 V	-13 + (WRHOLD * t _{HFCOR-ECLK})	—	—	ns
Output setup time, from EBI_AD, EBI_A, EBI_CS _n , EBI_BL _n valid to leading EBI_WEn / EBI_NANDWEn edge ¹	t _{OSU_WEn}	IOVDD ≥ 1.62 V	-12 + (WRSET-UP * t _{HFCOR-ECLK})	—	—	ns
		IOVDD ≥ 3.0 V	-10 + (WRSET-UP * t _{HFCOR-ECLK})	—	—	ns
EBI_WEn / EBI_NANDWEn pulse width ¹	t _{WIDTH_WEn}	IOVDD ≥ 1.62 V	-6 + (MAX(1, WRSTRB) * t _{HFCOR-ECLK})	—	—	ns
		IOVDD ≥ 3.0 V	-5 + (MAX(1, WRSTRB) * t _{HFCOR-ECLK})	—	—	ns

Note:

1. The figure shows the timing for the case that the half strobe length functionality is not used, i.e. HALFWE=0. The leading edge of EBI_WEn can be moved to the right by setting HALFWE=1. This decreases the length of t_{WIDTH_WEn} and increases the length of t_{OSU_WEn} by 1/2 * t_{HFCLKNODIV}.

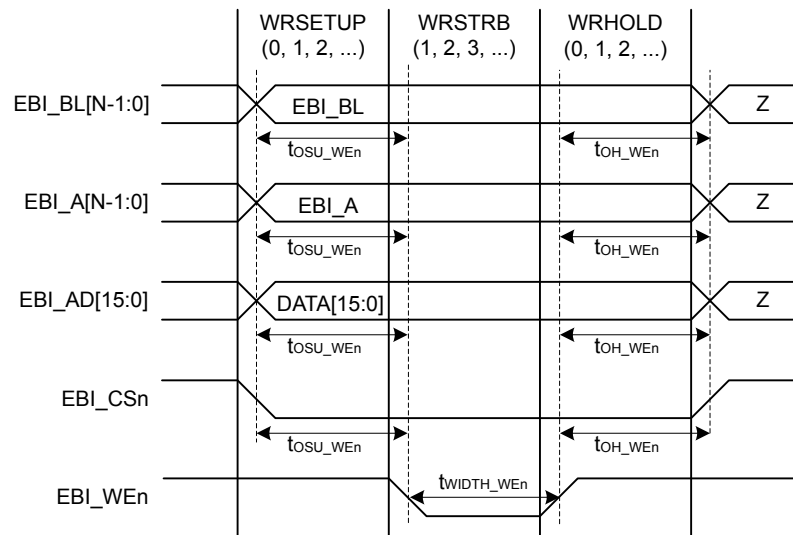


Figure 4.3. EBI Write Enable Output Timing Diagram

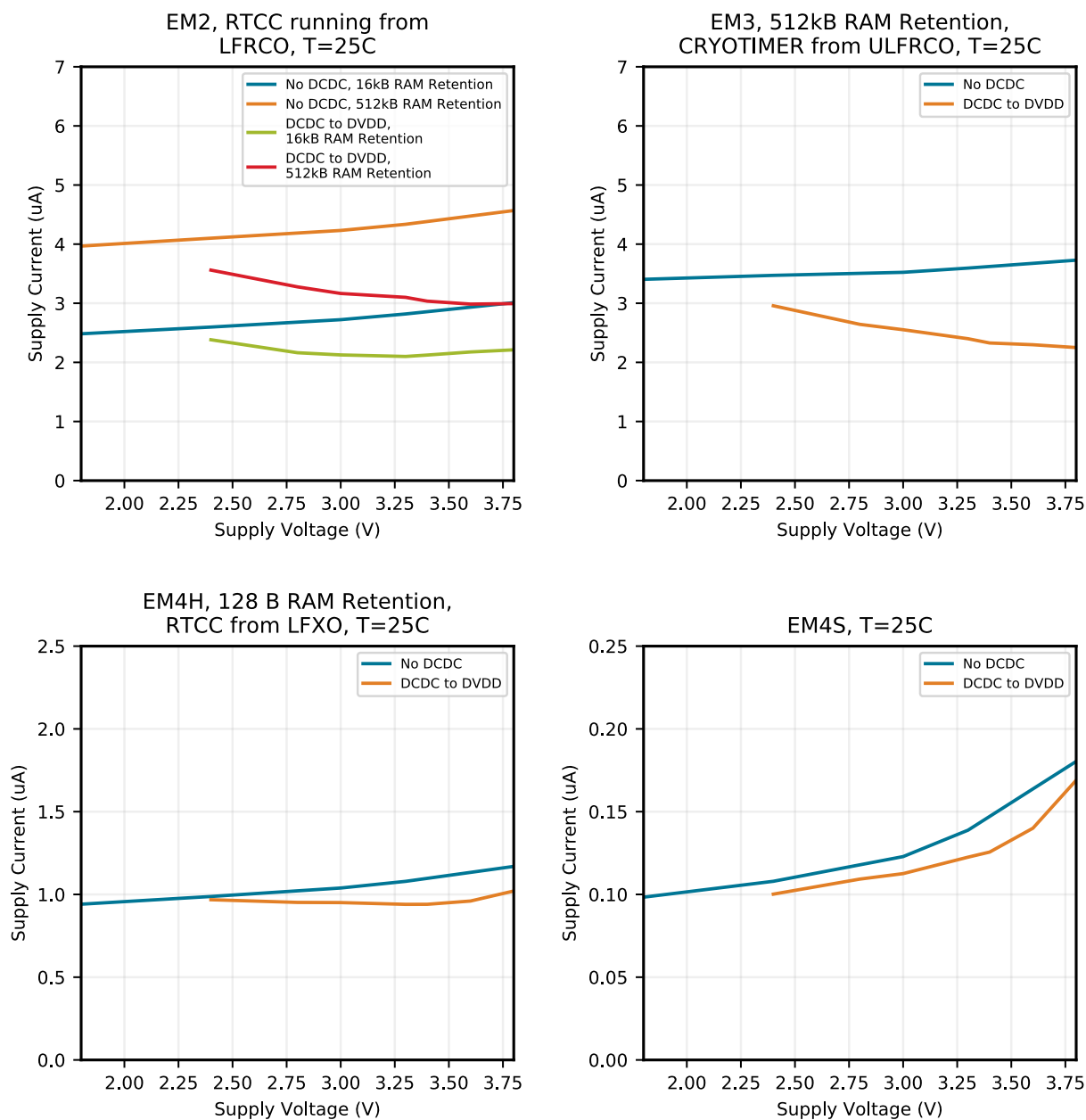


Figure 4.28. EM2, EM3, EM4H and EM4S Typical Supply Current vs. Supply

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PG6	H1	GPIO (5V)	PG7	H2	GPIO (5V)
PG5	H3	GPIO (5V)	PE6	H12	GPIO
PE5	H13	GPIO	DVDD	H14	Digital power supply.
PG9	J1	GPIO (5V)	PG10	J2	GPIO (5V)
PG8	J3	GPIO (5V)	PE3	J12	GPIO
PE4	J13	GPIO	VREGVDD	J14	Voltage regulator VDD input
PG12	K1	GPIO	PG13	K2	GPIO
PG11	K3	GPIO (5V)	PE2	K12	GPIO
PE1	K13	GPIO (5V)	VREGSW	K14	DCDC regulator switching node
PG15	L1	GPIO (5V)	PB15	L2	GPIO (5V)
PG14	L3	GPIO	PC7	L12	GPIO
PE0	L13	GPIO (5V)	VREGVSS	L14	Voltage regulator VSS
PB0	M1	GPIO	PB1	M2	GPIO
PB4	M3	GPIO	PC0	M4	GPIO (5V)
PC3	M5	GPIO (5V)	PA9	M6	GPIO
BODEN	M7	Brown-Out Detector Enable. This pin may be left disconnected or tied to AVDD.	PA12	M8	GPIO (5V)
RESETn	M9	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.	PB10	M10	GPIO (5V)
PD1	M11	GPIO	PC6	M12	GPIO
PD5	M13	GPIO	PD8	M14	GPIO
PB7	N1	GPIO	PB2	N2	GPIO
PB5	N3	GPIO	PC2	N4	GPIO (5V)
PC5	N5	GPIO	PA8	N6	GPIO
PA11	N7	GPIO	PA14	N8	GPIO
PB11	N9	GPIO	PB12	N10	GPIO
PD0	N11	GPIO (5V)	PD2	N12	GPIO (5V)
PD4	N13	GPIO	PD7	N14	GPIO
PB8	P1	GPIO	PB3	P2	GPIO
PB6	P3	GPIO	PC1	P4	GPIO (5V)
PC4	P5	GPIO	PA7	P6	GPIO
PA10	P7	GPIO	PA13	P8	GPIO (5V)
PB9	P9	GPIO (5V)	PB13	P10	GPIO
PB14	P11	GPIO	AVDD	P12	Analog power supply.
PD3	P13	GPIO	PD6	P14	GPIO

5.9 EFM32GG11B5xx in QFP100 Device Pinout

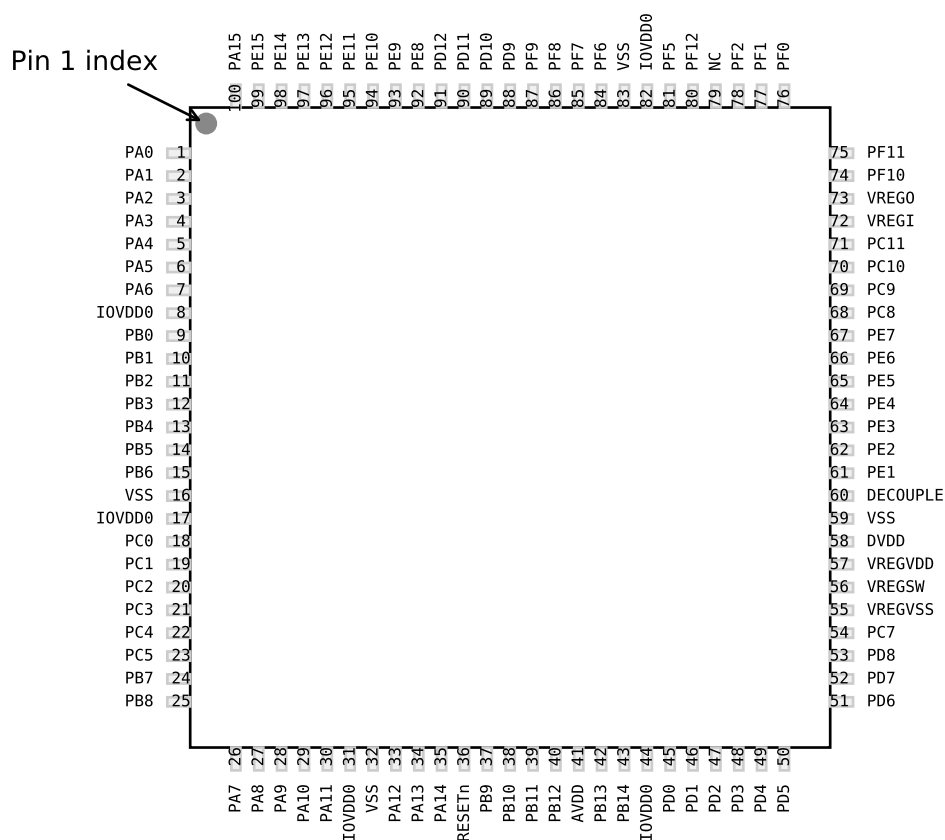


Figure 5.9. EFM32GG11B5xx in QFP100 Device Pinout

The following table provides package pin connections and general descriptions of pin functionality. For detailed information on the supported features for each GPIO pin, see [5.20 GPIO Functionality Table](#) or [5.21 Alternate Functionality Overview](#).

Table 5.9. EFM32GG11B5xx in QFP100 Device Pinout

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PA0	1	GPIO	PA1	2	GPIO
PA2	3	GPIO	PA3	4	GPIO
PA4	5	GPIO	PA5	6	GPIO
PA6	7	GPIO	IOVDD0	8, 17, 31, 44, 82	Digital IO power supply 0.
PB0	9	GPIO	PB1	10	GPIO

Pin Name	Pin(s)	Description	Pin Name	Pin(s)	Description
PC4	13	GPIO	PC5	14	GPIO
PB7	15	GPIO	PB8	16	GPIO
PA8	17	GPIO	PA9	18	GPIO
PA10	19	GPIO	RESETn	20	Reset input, active low. To apply an external reset source to this pin, it is required to only drive this pin low during reset, and let the internal pull-up ensure that reset is released.
PB11	21	GPIO	AVDD	23 27	Analog power supply.
PB13	24	GPIO	PB14	25	GPIO
PD0	28	GPIO (5V)	PD1	29	GPIO
PD2	30	GPIO (5V)	PD3	31	GPIO
PD4	32	GPIO	PD5	33	GPIO
PD6	34	GPIO	PD7	35	GPIO
PD8	36	GPIO	PC6	37	GPIO
PC7	38	GPIO	DVDD	39	Digital power supply.
DECOUPLE	40	Decouple output for on-chip voltage regulator. An external decoupling capacitor is required at this pin.	PC8	41	GPIO (5V)
PC9	42	GPIO (5V)	PC10	43	GPIO (5V)
PC11	44	GPIO (5V)	PC12	45	GPIO (5V)
PC13	46	GPIO (5V)	PC14	47	GPIO (5V)
PC15	48	GPIO (5V)	PF0	49	GPIO (5V)
PF1	50	GPIO (5V)	PF2	51	GPIO
PF3	52	GPIO	PF4	53	GPIO
PF5	54	GPIO	PE8	57	GPIO
PE9	58	GPIO	PE10	59	GPIO
PE11	60	GPIO	PE12	61	GPIO
PE13	62	GPIO	PE14	63	GPIO
PE15	64	GPIO			

Note:

1. GPIO with 5V tolerance are indicated by (5V).

GPIO Name	Pin Alternate Functionality / Description				
	Analog	EBI	Timers	Communication	Other
PE6	BUSDY BUSCX LCD_COM2	EBI_A13 #0 EBI_A18 #1 EBI_A24 #3	TIM3_CC1 #3 TIM5_CC2 #0 TIM6_CDTI2 #2 WTIM0_CC2 #0 WTIM1_CC3 #4	US0_RX #1 US3_TX #1	PRS_CH6 #2
PE7	BUSCY BUSDX LCD_COM3	EBI_A14 #0 EBI_A19 #1 EBI_A25 #3	TIM3_CC2 #3 TIM5_CC0 #1 WTIM1_CC0 #5	US0_TX #1 US3_RX #1	PRS_CH7 #2
PG11		EBI_AD11 #2	TIM6_CDTI2 #1 WTIM0_CDTI0 #3	ETH_MIIRXD0 #1 CAN1_TX #6 US3_RTS #5 QSPIO_DQS #2	ETM_TD3 #5
PG10		EBI_AD10 #2	TIM2_CC2 #6 TIM6_CDTI1 #1 WTIM0_CC2 #3	ETH_MIIRXD1 #1 CAN1_RX #6 US3_CTS #3 QSPIO_CS1 #2	
PG9		EBI_AD09 #2	TIM2_CC1 #6 TIM6_CDTI0 #1 WTIM0_CC1 #3	ETH_MIIRXD2 #1 CAN0_TX #4 US3_CTS #5 QSPIO_CS0 #2	
PE3	BU_STAT	EBI_A10 #0 EBI_A15 #1	TIM3_CC0 #2 WTIM1_CC0 #4	US0_CTS #1 U0_RTS #1 U1_RX #3	ACMP1_O #1
PE4	BUSDY BUSCX LCD_COM0	EBI_A11 #0 EBI_A16 #1 EBI_A22 #3	TIM3_CC1 #2 TIM5_CC0 #0 TIM6_CDTI0 #2 WTIM0_CC0 #0 WTIM1_CC1 #4	US0_CS #1 US1_CS #5 US3_CS #1 U0_RX #6 U1_CTS #3 I2C0_SDA #7	PRS_CH16 #2
PG14		EBI_AD14 #2	TIM6_CC2 #2 WTIM2_CC0 #4 PCNT1_S0IN #7	ETH_MIICRS #1 US0_CLK #6	ETM_TD0 #5
PG13		EBI_AD13 #2	TIM6_CC1 #2 WTIM0_CDTI2 #3 WTIM2_CC2 #3	ETH_MIIRXER #1 US0_RX #6	ETM_TD1 #5
PG12		EBI_AD12 #2	TIM6_CC0 #2 WTIM0_CDTI1 #3 WTIM2_CC1 #3	ETH_MIIRXDV #1 US0_TX #6	ETM_TD2 #5
PE1	BUSCY BUSDX	EBI_A01 #2 EBI_A08 #0	TIM3_CC1 #1 WTIM1_CC2 #3 PCNT0_S1IN #1	CAN0_TX #6 U0_RX #1 I2C1_SCL #2	CMU_CLKI0 #4 PRS_CH23 #1 ACMP2_O #2
PE2	BU_VOUT	EBI_A09 #0 EBI_A14 #1	TIM3_CC2 #1 WTIM1_CC3 #3	US0_RTS #1 U0_CTS #1 U1_TX #3	PRS_CH20 #2 ACMP0_O #1
PG15		EBI_AD15 #2	WTIM2_CC1 #4 PCNT1_S1IN #7	ETH_MIICOL #1 US0_CS #6	ETM_TCLK #5
PB15	BUSAY BUSBX	EBI_CS3 #1 EBI_AR- DY #2	TIM3_CC1 #7	ETH_TSUTMRTOG #1 SDIO_WP #2 US2_RTS #1 US5_RTS #1	PRS_CH17 #1 ETM_TD2 #1

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
EBI_A23	0: PC0 1: PC11 2: PH11 3: PE5		External Bus Interface (EBI) address output pin 23.
EBI_A24	0: PC1 1: PF0 2: PH12 3: PE6		External Bus Interface (EBI) address output pin 24.
EBI_A25	0: PC2 1: PF1 2: PH13 3: PE7		External Bus Interface (EBI) address output pin 25.
EBI_A26	0: PC4 1: PF2 2: PH14 3: PC8		External Bus Interface (EBI) address output pin 26.
EBI_A27	0: PD2 1: PF5 2: PH15 3: PC9		External Bus Interface (EBI) address output pin 27.
EBI_AD00	0: PE8 1: PB0 2: PG0		External Bus Interface (EBI) address and data input / output pin 00.
EBI_AD01	0: PE9 1: PB1 2: PG1		External Bus Interface (EBI) address and data input / output pin 01.
EBI_AD02	0: PE10 1: PB2 2: PG2		External Bus Interface (EBI) address and data input / output pin 02.
EBI_AD03	0: PE11 1: PB3 2: PG3		External Bus Interface (EBI) address and data input / output pin 03.
EBI_AD04	0: PE12 1: PB4 2: PG4		External Bus Interface (EBI) address and data input / output pin 04.
EBI_AD05	0: PE13 1: PB5 2: PG5		External Bus Interface (EBI) address and data input / output pin 05.
EBI_AD06	0: PE14 1: PB6 2: PG6		External Bus Interface (EBI) address and data input / output pin 06.
EBI_AD07	0: PE15 1: PC0 2: PG7		External Bus Interface (EBI) address and data input / output pin 07.

Alternate	LOCATION		
Functionality	0 - 3	4 - 7	Description
LFXTAL_N	0: PB8		Low Frequency Crystal (typically 32.768 kHz) negative pin. Also used as an optional external clock input pin.
LFXTAL_P	0: PB7		Low Frequency Crystal (typically 32.768 kHz) positive pin.
OPA0_N	0: PC5		Operational Amplifier 0 external negative input.
OPA0_P	0: PC4		Operational Amplifier 0 external positive input.
OPA1_N	0: PD7		Operational Amplifier 1 external negative input.
OPA1_P	0: PD6		Operational Amplifier 1 external positive input.
OPA2_N	0: PD3		Operational Amplifier 2 external negative input.
OPA2_OUT	0: PD5		Operational Amplifier 2 output.
OPA2_OUTALT	0: PD0		Operational Amplifier 2 alternative output.
OPA2_P	0: PD4		Operational Amplifier 2 external positive input.
OPA3_N	0: PC7		Operational Amplifier 3 external negative input.
OPA3_OUT	0: PD1		Operational Amplifier 3 output.
OPA3_P	0: PC6		Operational Amplifier 3 external positive input.

Table 5.23. ACMP0 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	BUSACMP0Y	BUSACMP0X	Bus
PF14	PF15	PF15	PF14	PB14	PB15	PB15	PB14			CH31
	PF13	PF13			PB13	PB13				CH30
PF12			PF12	PB12			PB12			CH29
	PF11	PF11			PB11	PB11				CH28
PF10			PF10	PB10			PB10			CH27
	PF9	PF9			PB9	PB9				CH26
PF8			PF8							CH25
	PF7	PF7								CH24
PF6			PF6	PB6			PB6			CH23
	PF5	PF5			PB5	PB5				CH22
PF4			PF4	PB4			PB4			CH21
	PF3	PF3			PB3	PB3				CH20
PF2			PF2	PB2			PB2			CH19
	PF1	PF1			PB1	PB1				CH18
PF0			PF0	PB0			PB0			CH17
	PE15	PE15			PA15	PA15				CH16
PE14			PE14	PA14			PA14			CH15
	PE13	PE13			PA13	PA13				CH14
PE12			PE12	PA12			PA12			CH13
	PE11	PE11			PA11	PA11				CH12
PE10			PE10	PA10			PA10			CH11
	PE9	PE9			PA9	PA9				CH10
PE8			PE8	PA8			PA8			CH9
	PE7	PE7			PA7	PA7		PC7	PC7	CH8
PE6			PE6	PA6			PA6	PC6	PC6	CH7
	PE5	PE5			PA5	PA5		PC5	PC5	CH6
PE4			PE4	PA4			PA4	PC4	PC4	CH5
					PA3	PA3		PC3	PC3	CH4
				PA2			PA2	PC2	PC2	CH3
	PE1	PE1			PA1	PA1		PC1	PC1	CH2
PE0			PE0	PA0			PA0	PC0	PC0	CH1
										CH0

Table 5.24. ACMP1 Bus and Pin Mapping

APORT4Y	APORT4X	APORT3Y	APORT3X	APORT2Y	APORT2X	APORT1Y	APORT1X	APORT0Y	APORT0X	Port
BUSDY	BUSDX	BUSCY	BUSCX	BUSBY	BUSBX	BUSAY	BUSAX	BUSACMP1Y	BUSACMP1X	Bus
PF14	PF15	PF15	PF14	PB14	PB15	PB15	PB14			CH31
	PF13	PF13			PB13	PB13				CH30
PF12			PF12	PB12			PB12			CH29
	PF11	PF11			PB11	PB11				CH28
PF10			PF10	PB10			PB10			CH27
	PF9	PF9			PB9	PB9				CH26
PF8			PF8							CH25
	PF7	PF7								CH24
PF6			PF6	PB6			PB6			CH23
	PF5	PF5			PB5	PB5				CH22
PF4			PF4	PB4			PB4			CH21
	PF3	PF3			PB3	PB3				CH20
PF2			PF2	PB2			PB2			CH19
	PF1	PF1			PB1	PB1				CH18
PF0			PF0	PB0			PB0			CH17
	PE15	PE15			PA15	PA15				CH16
PE14			PE14	PA14			PA14			CH15
	PE13	PE13			PA13	PA13				CH14
PE12			PE12	PA12			PA12			CH13
	PE11	PE11			PA11	PA11				CH12
PE10			PE10	PA10			PA10			CH11
	PE9	PE9			PA9	PA9				CH10
PE8			PE8	PA8			PA8			CH9
	PE7	PE7			PA7	PA7				CH8
PE6			PE6	PA6			PA6	PC15	PC15	CH7
	PE5	PE5			PA5	PA5		PC14	PC14	CH6
PE4			PE4	PA4			PA4	PC13	PC13	CH5
					PA3	PA3		PC12	PC12	CH4
				PA2			PA2	PC11	PC11	CH3
	PE1	PE1			PA1	PA1		PC10	PC10	CH2
								PC9	PC9	CH1
PE0			PE0	PA0			PA0	PC8	PC8	CH0

9. BGA112 Package Specifications

9.1 BGA112 Package Dimensions

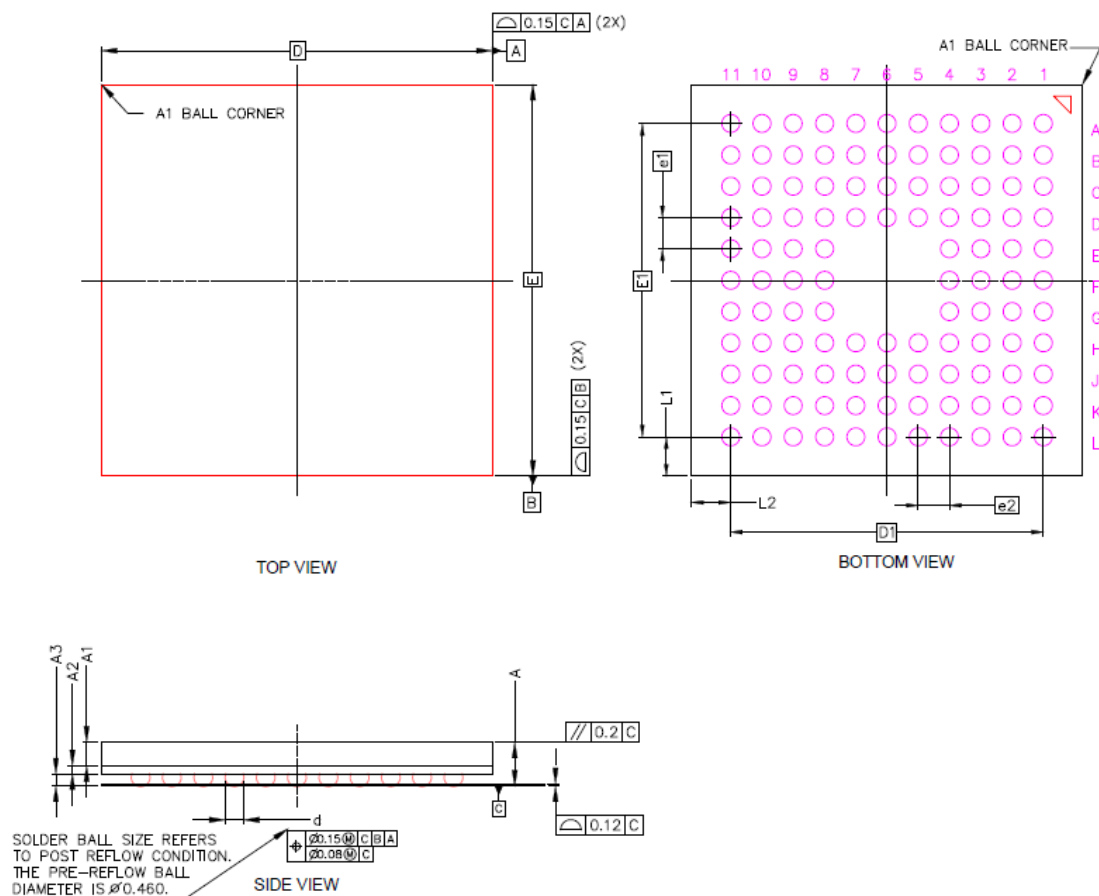


Figure 9.1. BGA112 Package Drawing

Table 12.1. QFN64 Package Dimensions

Dimension	Min	Typ	Max
A	0.70	0.75	0.80
A1	0.00	—	0.05
b	0.20	0.25	0.30
A3	0.203 REF		
D	9.00 BSC		
e	0.50 BSC		
E	9.00 BSC		
D2	7.10	7.20	7.30
E2	7.10	7.20	7.30
L	0.40	0.45	0.50
L1	0.00	—	0.10
aaa	0.10		
bbb	0.10		
ccc	0.10		
ddd	0.05		
eee	0.08		

Note:

1. All dimensions shown are in millimeters (mm) unless otherwise noted.
2. Dimensioning and Tolerancing per ANSI Y14.5M-1994.
3. Recommended card reflow profile is per the JEDEC/IPC J-STD-020 specification for Small Body Components.